

Technical Data Sheet



Culver International Ltd

Dynaloy European Manufacturers Agent

Establishing Distributors and Maintaining
The European Network for Dynaloy, Inc.



Engineered Chemistries

ISO 9001:2000

DYNASOLVE 180

Dynasolve 180 is used for dissolving cured urethanes and decapsulating cured epoxy systems. It is a safe but very aggressive product used in the urethane, electronics, and converting industries.

General

Dynasolve 180 is a unique blend of solvents designed for the disintegration of cured epoxy systems and the dissolving of various urethanes. It is not a true solvent for the epoxies but causes disintegration by flaking or breaking the cured epoxy system. It is a natural blend that will not discolor nor attack metal or plating commonly used in electronic assemblies. Dynasolve 180 does not contain phenol, chlorinated solvents, DMF, DMSO, strong acids, or bases.

Applications

1. Dynasolve 180 can be used for the disintegration of some cured epoxy systems.
2. Dynasolve 180 is an effective solvent at the removal of cured urethane, urethane foams, and crystallized isocyanates.
3. Dynasolve 180 will dissolve cured urethane adhesives used in the Oriented Strand Board Industry, Particle Board Industry, and other industrial woodworking applications.

Specifications

Color:	Clear to Light Amber
Specific Gravity:	1.03
Boiling Point:	396°F
Flash Point:	204°F(CC)

Directions For Use

FOR EPOXIES: Pour Dynasolve 180 into glass, aluminum or stainless steel container. Immerse component completely. Heat solution to 200°F. Cover container to prevent solvent loss. If epoxy does not disintegrate within 1 hour, raise the temperature of the solution up to 350-396°F. After epoxy has disintegrated, rinse with water or alcohol.

It may be necessary to suspend the component in solution so that the material removed will settle to the bottom of the container and not redeposit onto the component.

FOR URETHANES: Pour Dynasolve 180 into a steel container. Immerse part completely. Most urethanes and polyurethane foams will dissolve without heat in less than 8 hours. For quicker removal, heat the solution to 130-150°F. Use of ultrasonic cleaners or mechanical mixing of the solvent will also speed up the dissolving rate. Light brushing may be necessary to remove excessive build-up. After resin has been dissolved, rinse part with water.

Dynasolve 180 can be reused. Filtering off solid materials is recommended for continuous reuse. Dynasolve 180 will darken upon continued heating but this does not affect its ability.

Do not allow Dynasolve 180 to come into contact with liquid isocyanates or prepolymers, as it will lead to gelling of the solvent.

Materials of Construction

Materials of construction for tanks, pumps and containers: At room temperature mild steel, polyethylene or polypropylene containers are recommended. For elevated temperatures use 304 stainless tanks and tubing. Teflon gasket materials are recommended.

Caution and Warnings

Dynasolve 180 contains powerful organic solvents. It is harmful if inhaled or swallowed. Avoid breathing vapors or mist. Keep away from heat and flame. Avoid contact with eyes and skin. Wear gloves, safety glasses, and protective clothing when handling. Use with adequate ventilation. Refer to MSDS before use, for disposal, or additional safe handling.

The information in this sheet is based upon our own research and is considered accurate. However, we make no warranty either expressed or implied regarding accuracy and results to be obtained, because operating conditions of users are beyond our control.

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